

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	8	((("6326244") or ("2192734") or ("0276940"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/03/04 19:39
L4	260	(257/777 or 257/784 or 257/786). ccls. and (wire with (insulat\$4 or coat\$4)) and @ad<"19961209"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 19:44
L5	82	(438/612 or 438/617 or 438/666). ccls. and (wire with (insulat\$4 or coat\$4)) and @ad<"19961209"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 19:44
L7	493	semiconductor and ((chip or die) same (substrate or carrier or board)) and (insulat\$4 near10 wire) and via and @ad<"19961230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 19:45
L8	1516	semiconductor and ((chip or die) same (substrate or carrier or board)) and ((insulat\$4 or coat\$4) with wir\$3) and via and @ad<"19961230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:00
L9	1060	(257/773).ccls. and @ad<"19961230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:01
L11	44	(257/773).ccls. and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and trac\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:05
L12	14	(257/773).ccls. and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and ((without or no) with trac\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:10

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L14	785	(257/777 or 257/778).ccls. and @ad<"19961230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:11
L15	14	(257/777 or 257/778).ccls. and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and ((without or no) with trac\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:15
L16	785	(257/777 or 257/778).ccls. and @ad<"19961230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:15
L17	14	(257/777 or 257/778).ccls. and @ad<"19961230" and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and ((without or no) with trac\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:17
L19	275	(257/E23.01 or 257/E23.011).ccls. and @ad<"19961230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:17
L21	15	(257/E23.01 or 257/E23.011).ccls. and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and trac\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:21
L22	6	(257/E23.01 or 257/E23.011).ccls. and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and ((without or no) with trac\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:21
L23	835	(257/E23.02 or 257/E23.024 or 257/E23.025).ccls. and @ad<"19961230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:22

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L24	51	(257/E23.02 or 257/E23.024 or 257/E23.025).ccls. and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and (trac\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:27
L25	8	(257/E23.02 or 257/E23.024 or 257/E23.025).ccls. and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and ((without or no) with trac\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:23
L26	6801	(Semiconductor or die or chip) and (packag\$4 or interposer or carrier or substrate or board) and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and (trac\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:28
L27	1165	(Semiconductor or die or chip) and (packag\$4 or interposer or carrier or substrate or board) and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and ((without or no) with trac\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:28
L28	198	(Semiconductor or die or chip) and (packag\$4 or interposer or carrier or substrate or board) and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and ((without or no) with trac\$4) and ((insulat\$4 or coat\$4) with wir\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:31
L29	123	(Semiconductor or die or chip) and (packag\$4 or interposer or carrier or substrate or board) and @ad<"19961230" and (bond\$4 or pad) and wir\$3 and ((without or no) with trac\$4) and ((insulat\$4 or coat\$4) near4 wir\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 20:31